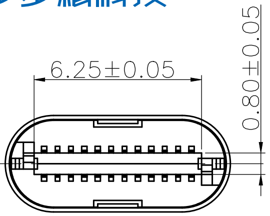
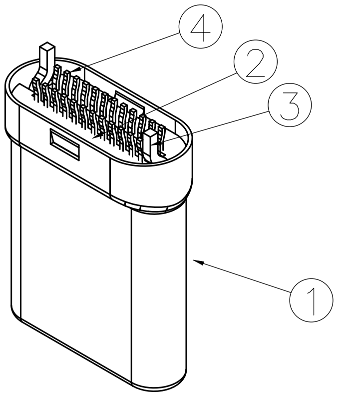
bbJconn
Since 1987 步步精科技

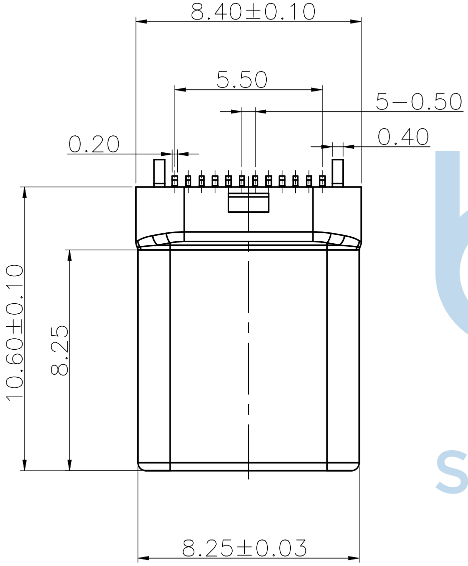
REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

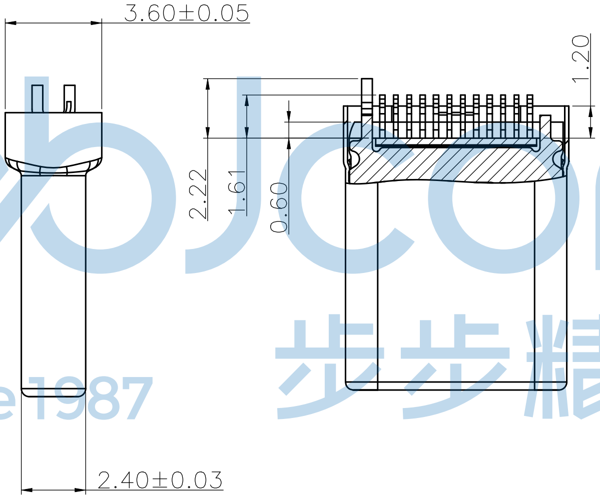




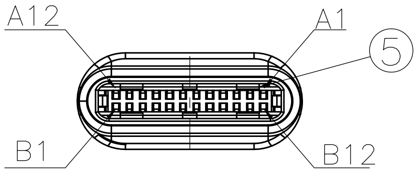
NOTES:
1.Material:SEE TABLE1;
2.Plating specification,
2-1.Contact:
Contact area: Ni50u"Min/Au See Table3;
Solder area: Ni50u"Min/Sn100u"Min.
Other area: Ni 50u"Min.
2-2.Shell:NI.
2-3.Latch:
Solder area: Ni50u"Min/Sn100u"Min.
Other area: Ni 50u"Min.
3.Mechanicl Performance ,
3-1.Insertion Force:5~20N;
3-2.Extraction Force:6~20N after 10000 cycles;
3-3.Durability:10000 cycles.
4.Electrical Performance,
4-1.Insulation Resistance:100? Min.
4-2.Contact Resistance :50m? Max.
4-3.Dielectic Strength :100V AC.
5.characteristic impedance:100 Ohm±10%;
6.Marked"▼" is the important control dimentions.
7.The product accords with HF STD.

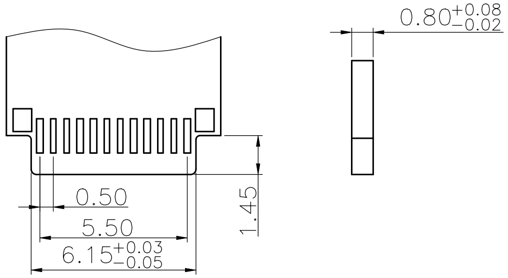
BBJconn Technology Co., Ltd
RoHS
Green Product Compliant





深圳市步步精科技有限公司
BBJconn
APPROVED
工程部
BBJconn Technology Co., Ltd





RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED ±0.05mm

TABLE1:

NO.	NAME	DESCRIPTION
5	EMC SPRING	Stainless Steel; SUS301,T=0.10mm;
4	CONTACT	Copper Alloy; AuNiSn;
3	LATCH	Stainless Steel; SUS301,T=0.40mm;
2	HOUSING	LCP Thermoplastic,UL94V-0;
1	SHELL	Stainless Steel; SUS316L,T=0.15mm;

TABLE2:
PINS DESCRIPTION,ONLY USED FOR 3.1 SERIES.

A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1
GND	RX2+	RX2-	VBUS	SBU1	D-	D+	CC	VBUS	TX1-	TX1+	GND
GND	TX2+	TX2-	VBUS	Vconn			SBU2	VBUS	RX1-	RX1+	GND
B1	B2	B3	B4	B5	B6	B7	B8	B9	B10	B11	B12

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.X: ±0.38	X°: ±3°
.XX: ±0.25	.X°: ±2°
.XXX: ±0.13	.XX°: ±1°

NAME: U4裸头 40速率 TYPE-C 24P 公头 直立式 夹板0.80 H=10.60 管装

APPD. JM_Zheng
CHKD. LYX
DR. TSP
PDWG,NO: 0500-1

PJ. NO.: 126-12A-240001-J8G
SIZE: A4
DRW NO.:
FINISH: SEE NOTES
MAT'L.: SEE NOTES
SCALE: N/A
REV.: A0
UNIT: mm
PAGE: 1/1